

FLUORITZ®-HS

◆ Concept

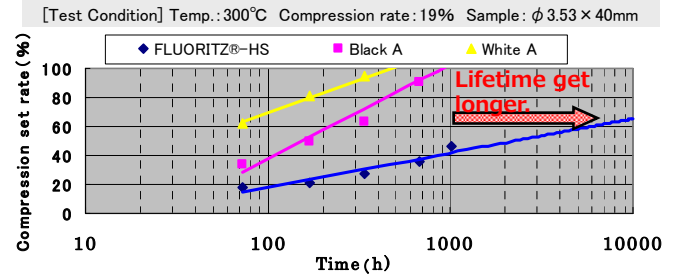
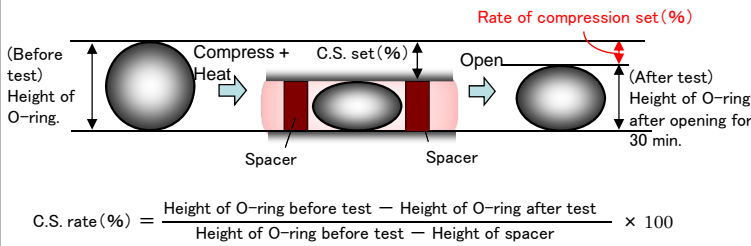
FFKM product with excellent heat resistance.

- ◆ Excellent heat resistance
Able to used up to 300°C.
Compression set rate is low in 300 °C service.

- ◆ Excellent purity
Metal content and outgassing amount is low.

◆ Properties

Heat Resistance (Compression Set)



Mechanical Properties

[Test Condition]
Hardness: Shore A
Tensile test: JIS K-6251

Appearance	Black color
Hardness	77
Tensile Strength (MPa)	20.0
Elongation (%)	160
Modulus 100%	9.3

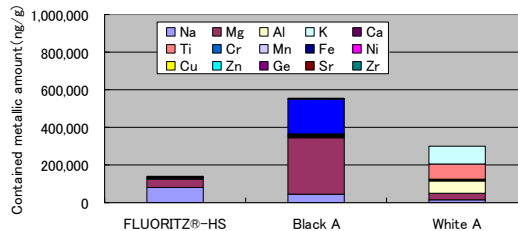
Chemical Resistance

Chemicals	FLUORITZ®-HS	Black A White A	FKM (4ClassD)
Acidum hydrochloricum	High	High	Moderate
Nitric acid	High	High	None
Acetic acid	High	High	None
Sodium hydroxide	High	High	None
Acetone	High	High	None
Methyl ethyl ketone	High	High	None
Ethyl acetate	High	High	None
Tetrahydrofuran	High	High	None
Dimethylformamide	High	High	None
Methanol	High	High	None
N-methylpyrrolidone	Moderate	Moderate	None
N-hexane	High	High	High
Benzene	High	High	Moderate
Steam	None	None	None

Purity

Contained metallic material

[Test Condition]
Pretreatment: Nitric acid ashing method
Measuring equipment: ICP-MS
Measuring element: 60
(Element below detection limit is not shown.)



Outgassing properties

[Test Condition]
Assay device: GC-MS
(Dynamic headspace method)
Heat Condition: 250°C × 30min
Outgassing amount: 1 μg / g
(Low detection limit)
*The amount is in a case of pentadecane conversion.

Presumed element	FLUORITZ®-HS	Black A	White A
Tetrafluorosilane	ND	110	ND
N-methyl-toluenesulfonamide	ND	8	4
Dibutyl phthalate	ND	2	2
Others	ND	ND	ND
Total outgassing amount	ND	120	6

This data is for reference by estimating from material structures. Resistance properties can be changed by environment like temp. or concentration etc. Thus, please kindly contact us before use.

◆ Suitable use

FLUORITZ®-HS



- Semiconductor**
- Plasma processing equipment (Etching / CVD equipments)
 - High temp. processing equipment (Diffusion / LPCVD / Anneal equipments)

- Chemical industry**
- Pump (Mechanical seal)
 - Compressor
 - Reactor, Stirring device

- Laboratory device**
- Assay device (GC-MS, TG, DTA, DSC, etc)

- Aerospace**
- Gas turbine engine

- Plastic/Rubber molding**
- Injection mold
 - Nozzle of injection molding
 - Extruding machine (Joint line of cylinder)